

PACKAGED MICROELECTRONIC DIE ASSEMBLIES
AND METHODS OF MANUFACTURE

ABSTRACT OF THE DISCLOSURE

Packaged microelectronic devices, interface substrates for packaging microelectronic devices, and methods of packaging single-die or stacked-die devices. One embodiment can include a die, an interface member having a die section attached to the die and an array section, and a casing encapsulating at least a portion of the die. The die section has a plurality of contacts coupled to bond-pads on the die, and the array section has an array of ball-pads coupled to the contacts by interconnecting circuitry in the interface member. The array section is folded over and/or under the die section, and the array section is attached to a backside of the die and/or a surface of the casing.

Figure 1